



IN THE U.S. PATENT AND TRADEMARK OFFICE

March 4, 2010

Applicants: Atsushi YABE et al

Title: ELECTROLESS COPPER PLATING SOLUTION

Serial No.: 10/576 231

Group: 1792

Confirmation No.: 7188

Filed: April 14, 2006

Examiner: Bareford

International Application No.: PCT/JP2004/011327

International Filing Date: July 30, 2004

Atty. Docket No.: 4700.P0327US

Mail Stop AF

Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

Sir:

Herewith is an amendment in the above-identified application.

☐ Applicant claims small entity status. See 37 CFR 1.27.

☐ The additional filing fee has been calculated as shown below:

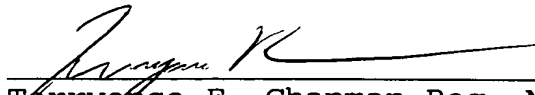
For	No. Filed	No. Extra	(X) LG Entity	RATE	() SM Entity	Fee
Total Claims	(8 - 20 = 0)		x	\$ 52.00	x	\$ 26.00
Indep. Claims	(3 - 3 = 0)		x	\$220.00	x	\$110.00
<input type="checkbox"/> Multiple Dep. Claim			+	\$390.00	+	\$195.00
* * * TOTAL FILING FEE * * *						\$ 0.00

☐ Pursuant to 37 CFR 1.136(a), please extend the shortened period for response by month(s). The extension fee is: \$.

☐ A Check for \$ is enclosed to cover fees.

☒ Please credit any overpayment, or charge any additional filing fee required under 37 CFR 1.16 or 1.17 by this communication, to Deposit Account No. 06-1382.

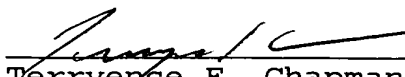
TFC/smd


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CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on March 4, 2010.

130.10/08


Terryence F. Chapman